

Final Product Change Notification

202308009F01: Etchant Material Discontinuation at NXP's Subcontractor Resulting in Bumping Process Change

Note: This notice is NXP Company Proprietary.

Issue Date: Sep 06, 2023 Effective date:Dec 05, 2023

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Management summary

Etchant material discontinuation at NXP's subcontractor resulting in bumping process change.

Change Category

Uswafer Fab Process	[X]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Firmware	[]Other			

PCN Overview

Description

Etchant Material Discontinuation at NXP's subcontractor resulting change in bumping process. Under Bump Metallization (UBM) and Re-distribution Layer (RDL) changes are as listed below.

Current Process: PBO1 + sputter RDL + PBO2 + sputter UBM

New Process: PBO1 + sputter & plate RDL + PBO2 + sputter & plate UBM

See attached Product Qualification Plan attached (pdf).

Reason

Etchant vendor is discontinuing an etchant material resulting in a bumping process change at ASEKH.

Identification of Affected Products

Top Side Marking

Product with date code 344 (YWW) and after will be assembled at ASEKH with NEW bumping process and materials.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipmentNov 17, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:view online Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Oct 06, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Orderable Part Number#	12NC	Product Type	Product Description	Product Status	Customer Specific Indicator	Product Line
LPC1102UK,118	935292625118	LPC1102UK	32 bit ARM M0 Core	RFS	No	BLM1
LPC11A02UK,118	935293059118	LPC11A02UK	32-bit ARM M0 Core	RFS	No	BLM1
LPC11A04UK,118	935297831118	LPC11A04UK	32-bit Cortex M0 Core	RFS	No	BLM1